

Global Chiplet-based Multi-die Advanced Packaging Market Growth 2026-2032

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Abstracts

The global Chiplet-based Multi-die Advanced Packaging market size is predicted to grow from US\$ 15456 million in 2025 to US\$ 44251 million in 2032; it is expected to grow at a CAGR of 15.4% from 2026 to 2032.

Chiplet-based multi-die advanced packaging refers to a class of semiconductor packaging manufacturing platforms and services that integrate two or more bare dies, chiplets, memory stacks, optical engines, analog/RF dies, I/O dies or other functional building blocks into a single high-performance package. The core process routes include silicon interposers, RDL interposers, silicon bridges, high-density fan-out, fan-out panel-level packaging, TSVs, hybrid bonding, chip-on-wafer, wafer-on-wafer, micro-bumps and copper-to-copper bonding. The focus of this study is on packaging technologies that improve die-to-die bandwidth, reduce interconnect power, shorten signal paths, increase system integration density and enable heterogeneous process-node combinations for AI accelerators, HPC processors, GPUs, data-center ASICs, HBM integration, networking chips, CPO, FPGAs, server CPUs, automotive compute and edge-AI applications.

Based on our research, chiplet-based multi-die advanced packaging has moved far beyond the traditional role of semiconductor assembly. Its core value is now system-level performance engineering. For AI accelerators and high-performance computing processors, performance scaling increasingly depends on how logic dies, HBM stacks, I/O dies, cache dies, photonic engines and specialty chiplets are interconnected within the package. These routes are not simple substitutes; they reflect different trade-offs among bandwidth, power, cost, package size, thermal constraints, yield and ecosystem control.

Demand growth is being driven most directly by AI GPUs, custom AI ASICs, HBM integration and high-end networking chips. The bandwidth and energy-efficiency bottleneck between logic and memory has made 2.5D/3D packaging a critical part of the AI server supply chain. At the same time, co-packaged optics, silicon photonics, automotive compute and edge AI are expanding the relevance of heterogeneous integration beyond hyperscale data centers. Regional semiconductor strategies are expanding from wafer fabs into high-end packaging capacity and back-end ecosystem build-out.

From a policy perspective, advanced packaging has become a strategic capability in the post-Moore era. The United States, South Korea, Japan, Taiwan and mainland China are all investing in packaging-related ecosystems. The U.S. NAPMP explicitly emphasizes heterogeneous integration and chiplet-based architectures, while China is pushing domestic alternatives through XDFOI, VISIONS, 2.5D/3D and FOPLP-related programs. The key bottlenecks for latecomers remain large-format interposers, HBM integration, advanced substrates, thermal management and qualification with top-tier AI/HPC customers.

Looking forward, competition will increasingly shift from individual packaging processes to integrated platforms combining advanced nodes, advanced packaging, HBM, substrates, thermal design, EDA/co-design and customer ecosystems. 2.5D packaging should remain the dominant route for AI/HPC in the medium term, while 3D stacking and hybrid bonding will gain penetration in cache, logic, memory and ultra-high-bandwidth systems. FOPLP and glass-substrate-based approaches may become important cost and form-factor alternatives. The main risk is not demand disappearance, but route substitution and capacity misallocation across competing packaging architectures.

LP Information, Inc. (LPI) ' newest research report, the "Chiplet-based Multi-die Advanced Packaging Industry Forecast" looks at past sales and reviews total world Chiplet-based Multi-die Advanced Packaging sales in 2025, providing a comprehensive analysis by region and market sector of projected Chiplet-based Multi-die Advanced Packaging sales for 2026 through 2032. With Chiplet-based Multi-die Advanced Packaging sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US\$ millions of the world Chiplet-based Multi-die Advanced Packaging industry.

This Insight Report provides a comprehensive analysis of the global Chiplet-based Multi-die Advanced Packaging landscape and highlights key trends related to product

segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Chiplet-based Multi-die Advanced Packaging portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Chiplet-based Multi-die Advanced Packaging market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Chiplet-based Multi-die Advanced Packaging and breaks down the forecast by Type, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Chiplet-based Multi-die Advanced Packaging.

This report presents a comprehensive overview, market shares, and growth opportunities of Chiplet-based Multi-die Advanced Packaging market by product type, application, key manufacturers and key regions and countries.

Segmentation by Type:

- 2.5D Advanced Packaging

- 3D Advanced Packaging

- Other Advanced Multi-die Packaging

Segmentation by Substrate / Carrier Type:

- Silicon Interposer

- Glass Interposer / Glass Core

- Other Carrier Types

Segmentation by Interconnect Technology:

Micro-bump Interconnect

TSV Interconnect

Other

Segmentation by Integration Object:

Logic-to-Logic Integration

Logic-to-Memory Integration

Logic-to-Analog/RF Integration

Other

Segmentation by Application:

Networking and Optical Communications

Industrial Electronics and Edge Computing

Aerospace and Defense Electronics

Medical and Life Science Electronics

Power and Energy Electronics

Other Specialty Electronics

This report also splits the market by region:

Americas

United States

Canada

Mexico

Brazil

APAC

China

Japan

Korea

Southeast Asia

India

Australia

Europe

Germany

France

UK

Italy

Russia

Middle East & Africa

Egypt

South Africa

Israel

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

Taiwan Semiconductor Manufacturing Company Limited

Samsung Electronics Co., Ltd.

Intel Corporation

ASE Technology Holding Co., Ltd.

Amkor Technology, Inc.

GlobalFoundries Inc.

JCET Group Co., Ltd.

Tongfu Microelectronics Co., Ltd.

Tianshui Huatian Technology Co., Ltd.

United Microelectronics Corporation

Powertech Technology Inc.

IBM Corporation

UTAC Holdings Ltd.

nepes Corporation

Deca Technologies Inc.

Forehope Electronic (Ningbo) Co., Ltd.

SkyWater Technology, Inc.

Micross Components, Inc.

Promex Industries, Inc.

NHanced Semiconductors, Inc.

Carsem (M) Sdn. Bhd.

Key Questions Addressed in this Report

What is the 10-year outlook for the global Chiplet-based Multi-die Advanced Packaging market?

What factors are driving Chiplet-based Multi-die Advanced Packaging market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Chiplet-based Multi-die Advanced Packaging market opportunities vary by end market size?

How does Chiplet-based Multi-die Advanced Packaging break out by Type, by Application?

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